Amendments to the Claims:

Claims 3, 7, 12, and 22 through 24 have been amended herein. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please cancel claims 4, 8, 13, 14, 17, 19, and 25 through 27. Please enter these claims as amended. Applicant respectfully submits that the amendment is supported in the specification as filed and that no new matter has been added. Applicant respectfully submits that FIG. 7 and paragraph [0031] of the Specification support the amendments to the claims.

This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

Claims 1-2 (Canceled)

3. (Currently Amended) A transfer molding apparatus comprising:
first and second members configured to be assembled with one another;
at least one encapsulant restraining cavity formed in at least one of said first and second members, said at least one cavity extending longitudinally in a non-horizontal orientation;
at least one gate at a lower portion of said at least one cavity;
at least one vent at an upper portion of said at least one cavity; and
wherein said at least one cavity includes at least one surface with recesses formed therein, each of said recesses having an imperforate boundary wall that is sized and configured to at least partially substantially conformally receive one of a plurality of conductive structures protruding from a substrate positionable in said at least one cavity.

Claims 4-6 (Canceled)

7. (Currently Amended) A transfer molding apparatus comprising:
first and second members to be assembled with one another;

at least one encapsulant restraining cavity formed in at least one of said first and second members, said at least one cavity extending longitudinally in a substantially vertical orientation;

at least one gate at a lower portion of said at least one cavity;

at least one vent at an upper portion of said at least one cavity; and

wherein said at least one cavity includes at least one surface with recesses formed therein, each of said recesses defined by an imperforate boundary wall ~~including portions~~that is sized and configured to substantially conformally receive one of a plurality of conductive structures protruding from a substrate positionable in said at least one cavity.

Claims 8-11 (Canceled)

12. (Currently Amended) A transfer molding apparatus for molding a substrate in a substantially vertical orientation, the apparatus comprising:

a first member and a second member configured to be assembled with one another, each of said first member and said second member having an inside surface and an outside surface;

multiple encapsulant restraining cavities each formed in said inside surface of at least one of said first member and said second member, each of said multiple cavities sized and configured for the substrate to be disposed therein, said multiple cavities extending longitudinally in a non-horizontal orientation;

at least one gate formed in any one of said first member and said second member extending from a lower portion of each of said multiple cavities; ~~and~~

at least one vent formed in any one of said first member and said second member extending from an upper portion of each of said multiple cavities; and

wherein at least one of said multiple cavities includes recesses formed in said inside surface on said at least one of said first member and said second member, each of said recesses defined by an imperforate boundary wall that is sized and configured to substantially conformally at least partially receive one of a plurality of conductive structures protruding from the substrate positionable in said at least one of said multiple cavities.

Claims 13-14 (Cancelled)

15. (Previously presented) The transfer molding apparatus of claim 12, wherein said multiple cavities are configured and longitudinally oriented to provide a substantially vertical flow for encapsulation of the substrate positionable in said multiple cavities.

16. (Previously presented) The apparatus according to claim 3, wherein said at least one cavity comprises a substantially vertically oriented cavity.

Claim 17 (Cancelled)

18. (Previously presented) The apparatus according to claim 7, wherein said at least one cavity is configured to provide a substantially vertical flow for encapsulation of a substrate positionable in said at least one cavity.

Claim 19 (Cancelled)

20. (Previously presented) The transfer molding apparatus of claim 12, wherein each of said multiple cavities comprises a substantially vertically oriented cavity.

21. (Previously presented) The transfer molding apparatus of claim 12, wherein each of said multiple cavities includes a longitudinal length substantially oriented along a substantially vertical orientation.

22. (Currently amended) The transfer molding apparatus of claim ~~13~~3, wherein the plurality of conductive structures comprise pillars or columns ~~each of said multiple cavities comprises a substantially vertically oriented cavity~~.

23. (Currently amended) The transfer molding apparatus of claim ~~13~~7, wherein the plurality of conductive structures comprise pillars or columns~~each of said multiple cavities includes a longitudinal length substantially oriented along a substantially vertical orientation~~.

24. (Currently amended) The transfer molding apparatus of claim ~~14~~12, wherein the plurality of conductive structures comprise pillars or columns~~each of said multiple cavities comprises a substantially vertically oriented cavity~~.

Claims 25-27 (Cancelled)